

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.80327	100.0	13.59
			<b>Subtotal</b>	<b>0.80327</b>	<b>100</b>	<b>13.59</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0188	100.0	0.31809
	Pure metal	Aluminium (Al)	7429-90-5	0.38302	100.0	6.48
			<b>Subtotal</b>	<b>0.40182</b>	<b>200</b>	<b>6.79809</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02085	2.0	0.3528
	Lead alloy	Silver (Ag)	7440-22-4	0.02607	2.5	0.441
	Lead alloy	Lead (Pb)	7439-92-1	0.99574	95.5	16.8462
			<b>Subtotal</b>	<b>1.04266</b>	<b>100</b>	<b>17.64</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01271	0.03	0.2151
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01271	0.03	0.2151
	Copper alloy	Iron (Fe)	7439-89-6	0.04238	0.1	0.717
	Copper alloy	Copper (Cu)	7440-50-8	42.31238	99.84	715.8528
			<b>Subtotal</b>	<b>42.38018</b>	<b>100</b>	<b>717</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.04394	3.8	34.58
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.22728	6.0	54.6
	Filler	Silica fused	60676-86-0	48.40917	90.0	819
	Carbon Black	Carbon black	1333-86-4	0.10758	0.2	1.82
			<b>Subtotal</b>	<b>53.78797</b>	<b>100</b>	<b>910</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.47769	100.0	25
			<b>Subtotal</b>	<b>1.47769</b>	<b>100</b>	<b>25</b>
Coating		Ethanol	64-17-5	0.10427	98.0	1.764
		3-aminopropyltriethoxysilane	919-30-2	0.00213	2.0	0.036
			<b>Subtotal</b>	<b>0.1064</b>	<b>100</b>	<b>1.8</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>1691.82809</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.